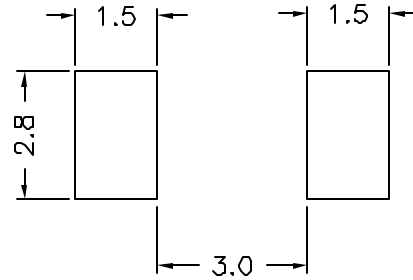
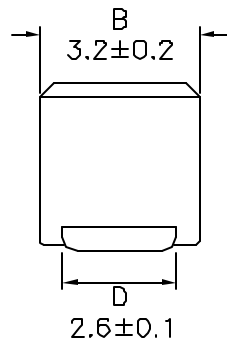
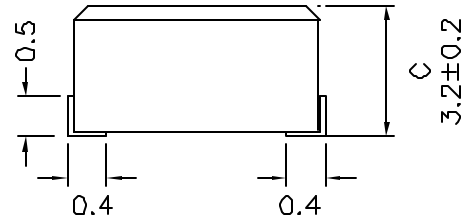
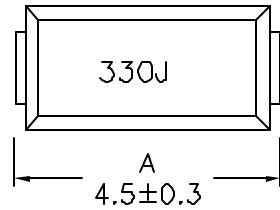
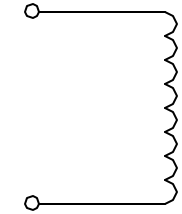


## 1. Mechanical Dimensions:



PCB Layout

## 2. Schematic:



## 3. Electrical Specifications:

OCL: 33uH±5% @2.52MHz  
 DCR: 4.0 Ohms Max  
 Rated DC Current: 160mA Max  
 Q: 50 Min @2.52MHz  
 SRF: 11MHz Min

### Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151558
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC REV: A/2

<b>XFMRs Inc</b> www.XFMRs.com	Title: <b>Wire Wound Chip Ind.</b>		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xx ±0.25 Dimensions in MM	P/N: XFWI453232-330J	REV. A
Scale 2.5:1 SHT 1 OF 1	DWN.	Xianyi	Jan-22-09
	CHK.	YK Liao	Jan-22-09
	APP.	Joe Huff	Jan-22-09